

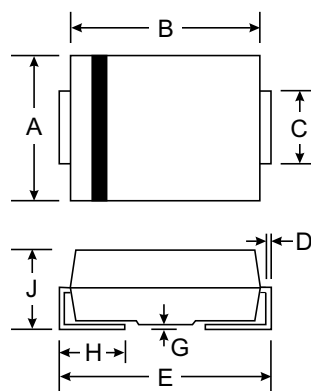
VOLTAGE RANGE: 50 - 1000V
CURRENT: 2.0 A

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop and High Current Capability
- Ideally Suited for Automated Assembly

Mechanical Data

- Case: SMA/DO-214AC, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.064 grams (approx.)



SMA(DO-214AC)		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SA2A	SA2B	SA2D	SA2G	SA2J	SA2K	SA2M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _T = 100°C	I _(AV)	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	55							A
Forward Voltage @ I _F = 2.0A	V _{FM}	0.845							V
Peak Reverse Current @ T _A = 25°C @ T _A = 125°C	I _{RM}	3.0 90							μA
Typical Total Capacitance (Note 1)	C _T	11							pF
Typical Thermal Resistance, Junction to Terminal (Note 2)	R _{θJT}	16							°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150							°C

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
2. Thermal Resistance Junction to Terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25^\circ\text{C}$ unless otherwise noted)

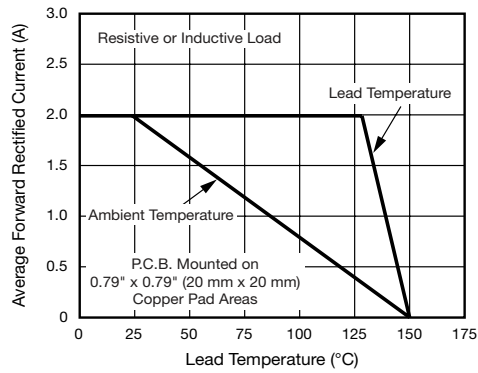


Fig. 1 - Maximum Forward Current Derating Curve

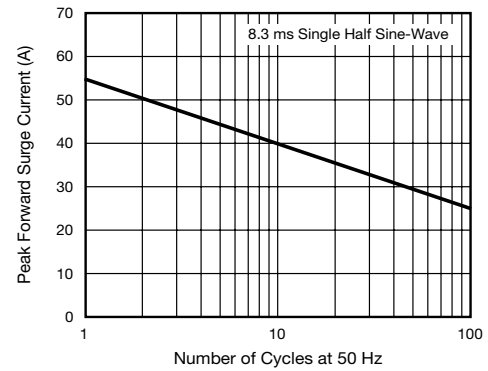


Fig. 3 - Maximum Non-Repetitive Peak Forward Surge Current

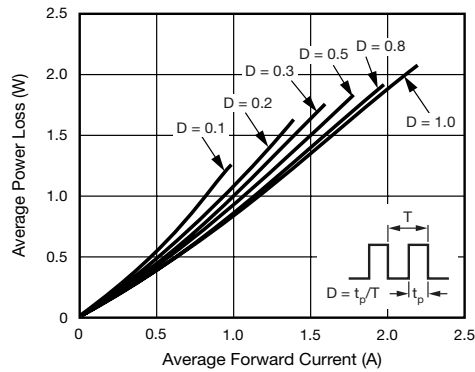


Fig. 2 - Forward Power Loss Characteristics

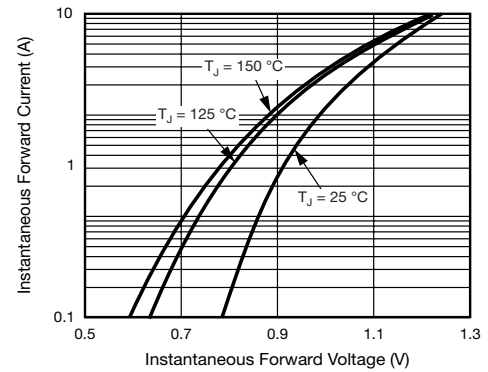


Fig. 4 - Typical Instantaneous Forward Characteristics

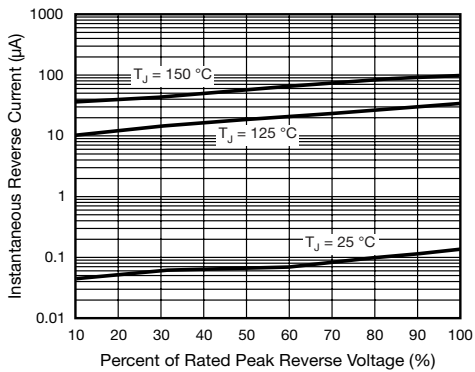


Fig. 5 - Typical Reverse Leakage Characteristics

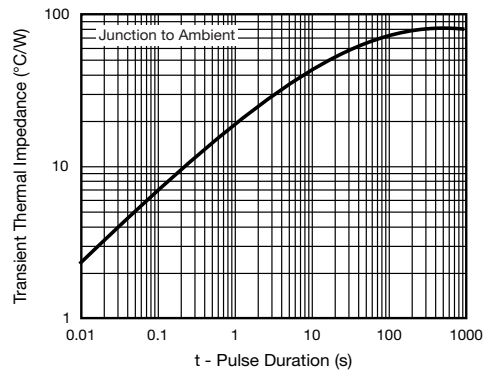


Fig. 7 - Typical Transient Thermal Impedance

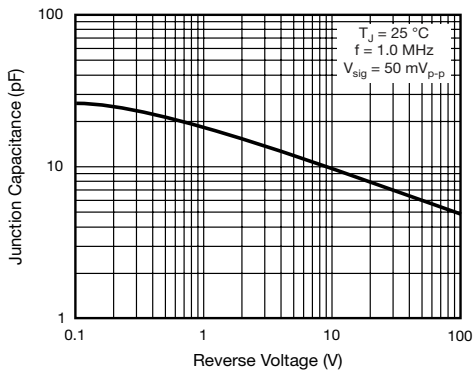


Fig. 6 - Typical Junction Capacitance